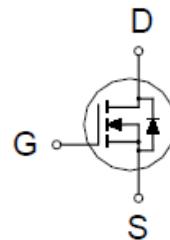
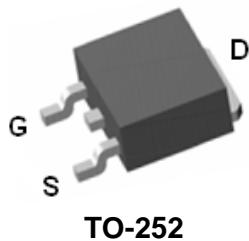


# PD506BA

## N-Channel Enhancement Mode MOSFET

### PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	$I_D$
30V	6mΩ @ $V_{GS} = 10V$	70A



### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ C$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS	UNITS
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>2</sup>	$I_D$	70	A
$T_C = 100^\circ C$		44	
Pulsed Drain Current <sup>1</sup>	$I_{DM}$	160	
Avalanche Current	$I_{AS}$	34	
Avalanche Energy	$E_{AS}$	57	mJ
Power Dissipation	$P_D$	50	W
$T_C = 100^\circ C$		20	
Junction & Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	°C

### THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		2.5	°C / W
Junction-to-Ambient	$R_{\theta JA}$		62.5	

<sup>1</sup>Pulse width limited by maximum junction temperature.

<sup>2</sup>Package limitation current is 60A

# PD506BA

## N-Channel Enhancement Mode MOSFET

### ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
<b>STATIC</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	30			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1.2	1.7	3.0	
Gate-Body Leakage	$I_{\text{GSS}}$	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 24\text{V}, V_{\text{GS}} = 0\text{V}$			1	$\mu\text{A}$
		$V_{\text{DS}} = 20\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 125^\circ\text{C}$			10	
Drain-Source On-State Resistance <sup>1</sup>	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = 4.5\text{V}, I_D = 15\text{A}$		5.2	9	$\text{m}\Omega$
		$V_{\text{GS}} = 10\text{V}, I_D = 20\text{A}$		4.3	6	
Forward Transconductance <sup>1</sup>	$g_{\text{fs}}$	$V_{\text{DS}} = 5\text{V}, I_D = 20\text{A}$		100		S
<b>DYNAMIC</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 15\text{V}, f = 1\text{MHz}$		1800		pF
Output Capacitance	$C_{\text{oss}}$			260		
Reverse Transfer Capacitance	$C_{\text{rss}}$			181		
Gate Resistance	$R_g$	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 0\text{V}, f = 1\text{MHz}$		0.96		$\Omega$
Total Gate Charge <sup>2</sup>	$Q_g$	$V_{\text{DS}} = 15\text{V}, V_{\text{GS}} = 10\text{V}, I_D = 20\text{A}$		34.7		nC
Gate-Source Charge <sup>2</sup>	$Q_{\text{gs}}$			5.5		
Gate-Drain Charge <sup>2</sup>	$Q_{\text{gd}}$			7.9		
Turn-On Delay Time <sup>2</sup>	$t_{\text{d}(\text{on})}$	$V_{\text{DS}} = 15\text{V}, I_D \approx 20\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 6\Omega$		10		nS
Rise Time <sup>2</sup>	$t_r$			24		
Turn-Off Delay Time <sup>2</sup>	$t_{\text{d}(\text{off})}$			99		
Fall Time <sup>2</sup>	$t_f$			57		
<b>SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (<math>T_J = 25^\circ\text{C}</math>)</b>						
Continuous Current <sup>3</sup>	$I_S$				70	A
Forward Voltage <sup>1</sup>	$V_{\text{SD}}$	$I_F = 20\text{A}, V_{\text{GS}} = 0\text{V}$			1.2	V
Reverse Recovery Time	$t_{\text{rr}}$	$I_F = 20\text{A}, dI_F/dt = 100\text{A}/\mu\text{s}$		18		nS
Reverse Recovery Charge	$Q_{\text{rr}}$			8.4		nC

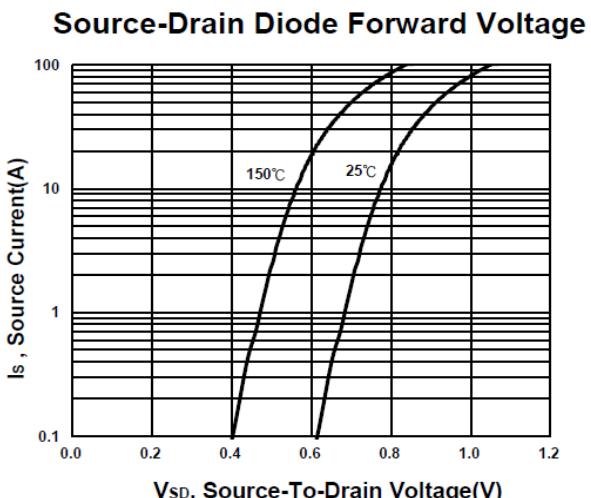
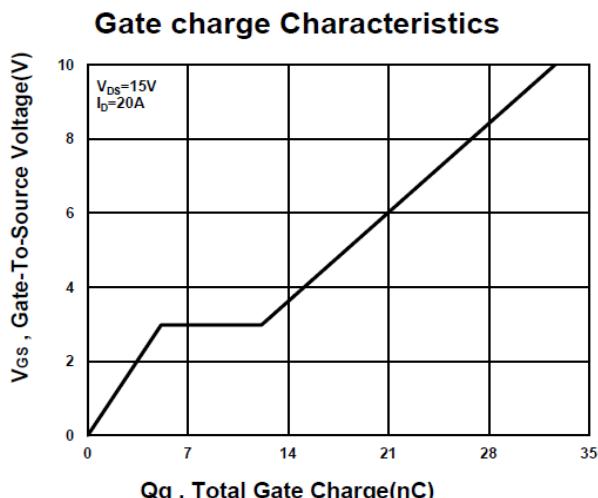
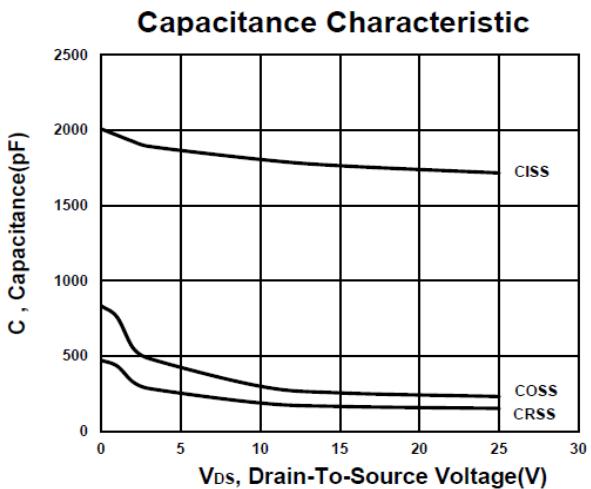
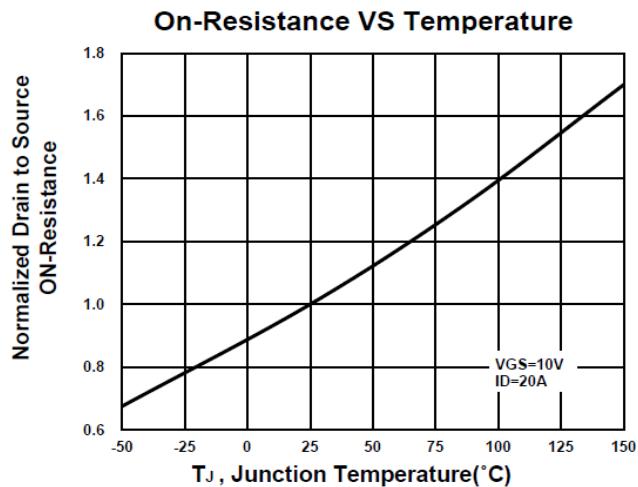
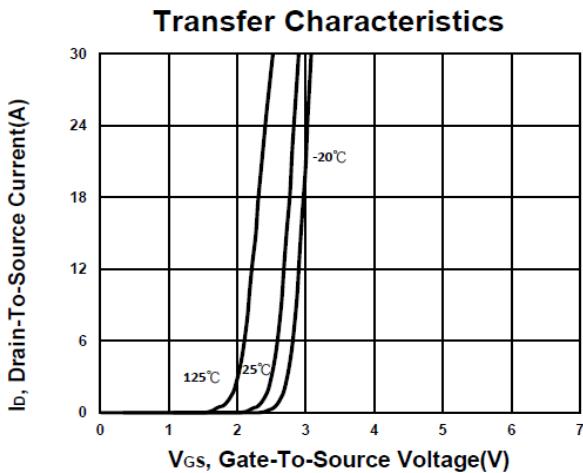
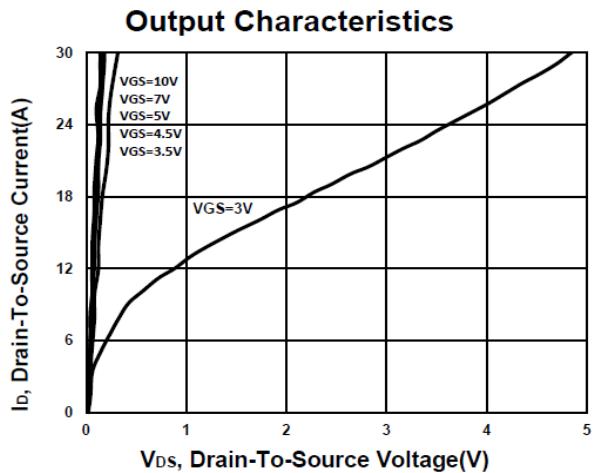
<sup>1</sup>Pulse test : Pulse Width  $\leq 300\ \mu\text{sec}$ , Duty Cycle  $\leq 2\%$ .

<sup>2</sup>Independent of operating temperature.

<sup>3</sup>Package limitation current is 60A

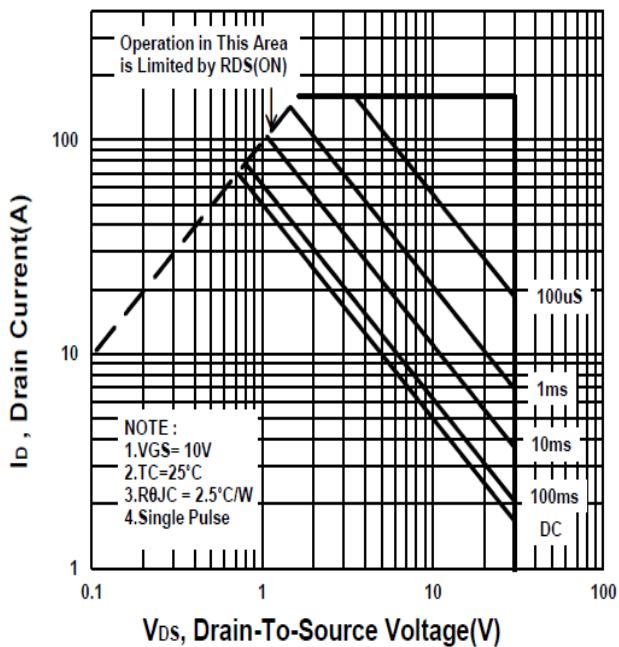
## PD506BA

### N-Channel Enhancement Mode MOSFET

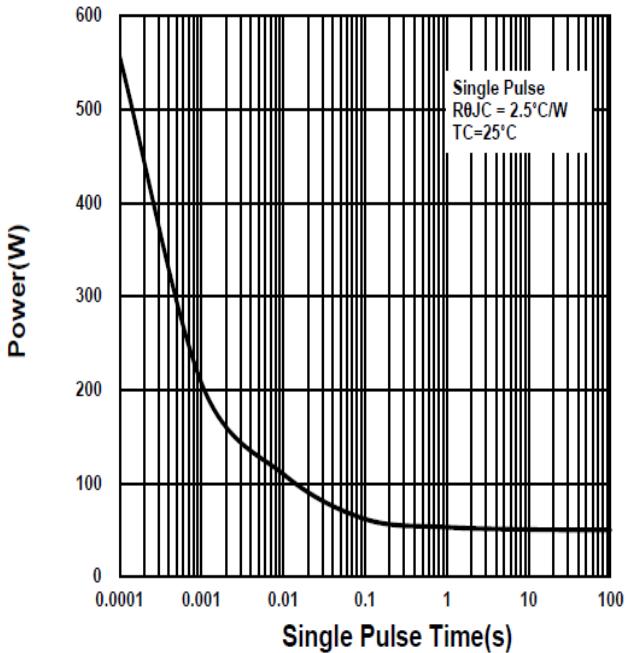


## PD506BA N-Channel Enhancement Mode MOSFET

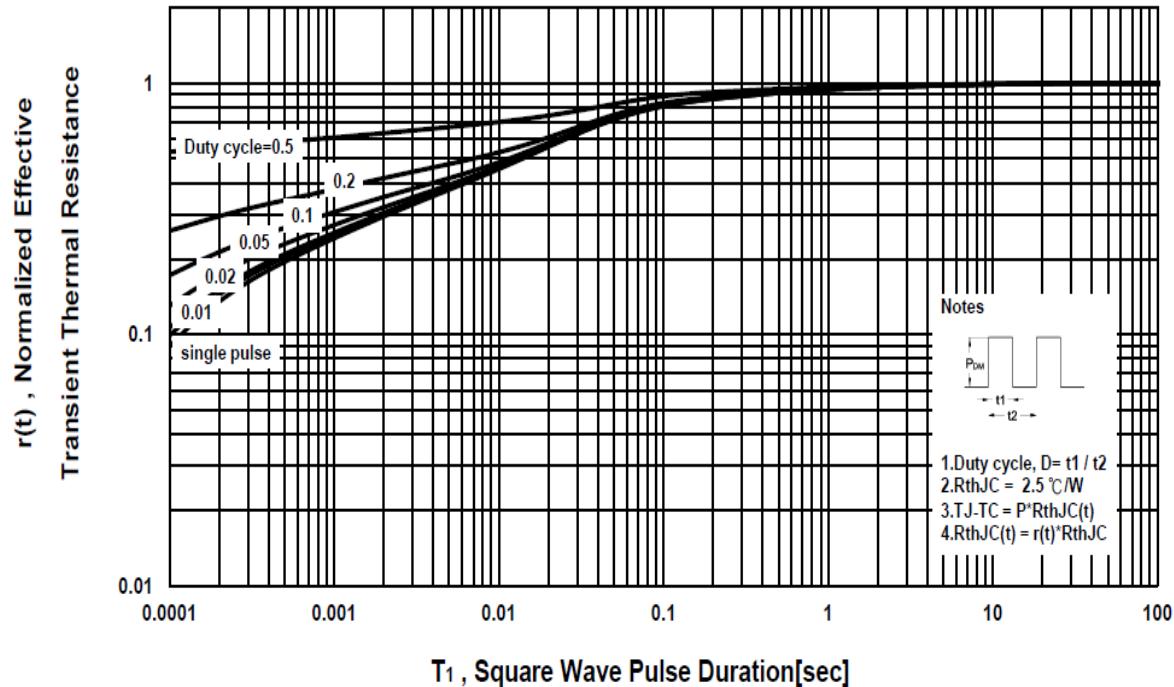
**Safe Operating Area**



**Single Pulse Maximum Power Dissipation**



**Transient Thermal Response Curve**



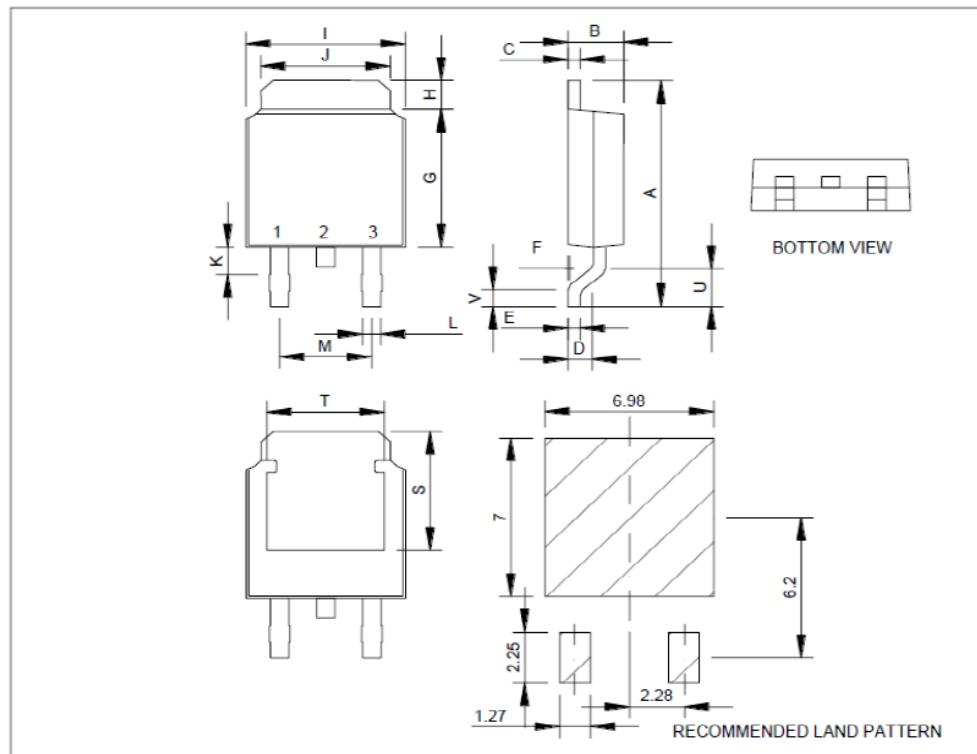
# PD506BA

## N-Channel Enhancement Mode MOSFET

### Package Dimension

#### TO-252 (DPAK) MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	8.9	10	10.41	J	4.8		5.64
B	2.1	2.2	2.4	K	0.15		1.1
C	0.4	0.5	0.61	L	0.4	0.76	0.89
D	0.82	1.2	1.5	M	4.2	4.58	5
E	0.4	0.5	0.61	S	4.9	5.1	5.3
F	0		0.2	T	4.6	4.75	5.44
G	5.3	6.1	6.3	U	1.4		1.78
H	0.9		1.7	V	0.55	1.25	1.7
I	6.3	6.5	6.8				



\*因为各家封装模具不同而外观略有差异，不影响电性及layout.